

In the Claims:

1       1. (Original) An electronic device (1)  
2            - with a base plate (2),  
3            - with an electronics housing (3) which is connected to  
4            the base plate (2), with at least one bond contact  
5            bearer (5),  
6           **characterised in that** the bond contact bearer (5) is  
7            supported on the base plate (2) by a supporting body (6) in  
8            such a manner that the supporting body (6) exerts a  
9            pretension force onto the bond contact bearer (5).

1       2. (Original) An electronic device according to claim 1,  
2           **characterised in that** a projection of the supporting body  
3           (6) above the base plate (2) is greater than the distance  
4           between the bond contact bearer (5) and the base plate (2).

Claims 3 and 4 (Canceled).

1       5. (Original) A procedure for bonding an electronic device (1)  
2           with the following procedural stages:  
3            - provision of a base plate (2),  
4            - connection of an electronics housing (3) via a  
5            supporting body (6) with the base plate (2) in such a

6 manner that the supporting body (6) exerts a  
7 pretension force onto the bond contact bearer (5),  
8 - creation of a bond connection between the bond contact  
9 bearer (5) of the electronics housing (3) and an  
10 additional bond contact bearer.

[REMARKS FOLLOW ON NEXT PAGE]